



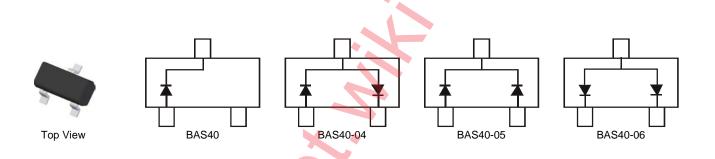
### SURFACE MOUNT SCHOTTKY BARRIER DIODE

### **Features**

- Low Forward Voltage Drop
- Fast Switching
- PN Junction Guard Ring for Transient and ESD Protection
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

## **Mechanical Data**

- Case: SOT23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Solderable per MIL-STD-202, Method 208 (3)
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Polarity: See Diagrams Below
- Weight: 0.008 grams (approximate)



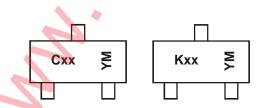
### Ordering Information (Note 4 & 5)

Part Number	Case	Packaging
BAS40-7-F	SOT23	3000/Tape & Reel
BAS40-04-7-F	SOT23	3000/Tape & Reel
BAS40-05-7-F	SOT23	3000/Tape & Reel
BAS40-06-7-F	SOT23	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.
- 5. Product manufactured with Date Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb<sub>2</sub>O<sub>3</sub> Fire Retardants.

## **Marking Information**



K=(SAT,Shangbai Assembly / test site)
C=(CAT / DTC , ChengDu Assembly / test site)

xx = Product Type Marking Code:

43 = BAS40

44 = BAS40-04

45 = BAS40-05

46 = BAS40-06

YM = Date Code Marking

Y = Year (ex: T = 2006)

M = Month (ex: 9 = September)

Date Code Key

Year	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	K	L	М	N	Р	R	S	Т	U	V	W	Χ	Υ	Z	Α	В	С
Month	Jan	F	-eb	Mar	Α	or	May	Jur	1	Jul	Aug	S	ер	Oct	No	v	Dec
Code	1		2	3	4	1	5	6		7	8	,	9	0	N		D



## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	40	V
Forward Continuous Current (Note 6)	I <sub>FM</sub>	200	mA
Forward Surge Current (Note 6) @ t < 1.0s	I <sub>FSM</sub>	600	mA

## **Thermal Characteristics**

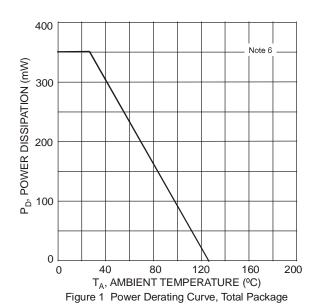
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	$P_{D}$	350	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	$R_{ hetaJA}$	357	°C/W
Operating Temperature Range	$T_J$	-55 to +125	°C
Storage Temperature Range	T <sub>STG</sub>	-65 to +150	°C

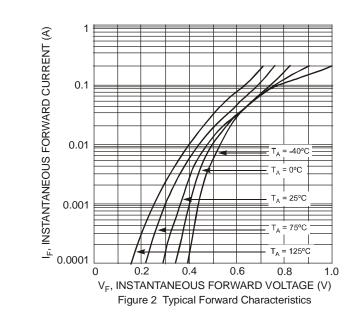
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	40			V	$I_R = 10\mu A$
Forward Voltage	V <sub>F</sub>	_	_	380 1000		$t_p < 300 \mu s$ , $I_F = 1.0 mA$ $t_p < 300 \mu s$ , $I_F = 40 mA$
Reverse Leakage Current (Note 7)	I <sub>R</sub>	_	20	200	nA	$t_p < 300 \mu s$ , $V_R = 30 V$
Total Capacitance	C <sub>T</sub>	_	4.0	5.0	pF	$V_R = 0V$ , $f = 1.0MHz$
Reverse Recovery Time	t <sub>rr</sub>	_		5.0	ns	$I_F = I_R = 10$ mA to $I_R = 1.0$ mA, $R_L = 100\Omega$

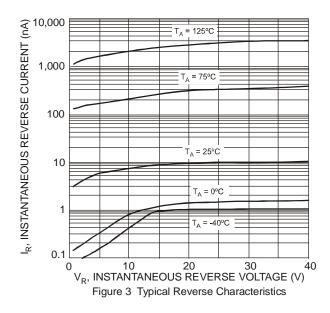
Notes:

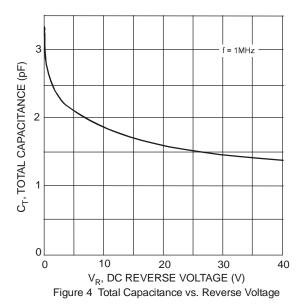
- 6. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 7. Short duration pulse test used to minimize self-heating effect.





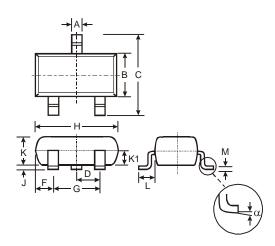






# **Package Outline Dimensions**

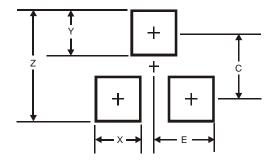
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SOT23									
Dim	Min	Max	Тур							
Α	0.37	0.51	0.40							
В	1.20	1.40	1.30							
С	2.30	2.50	2.40							
D	0.89	1.03	0.915							
F	0.45	0.60	0.535							
G	1.78	2.05	1.83							
Н	2.80	3.00	2.90							
J	0.013	0.10	0.05							
K	0.903	1.10	1.00							
K1	-	1	0.400							
L	0.45	0.61	0.55							
M	0.085	0.18	0.11							
α	0°	8°	-							
All	All Dimensions in mm									

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Υ	0.9
С	2.0
E	1.35



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